

## N-Ch 30V Fast Switching MOSFETs

### Product Summary



- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent  $CdV/dt$  effect decline
- ★ Advanced high cell density Trench technology

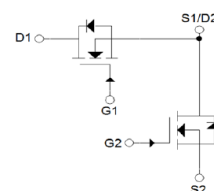
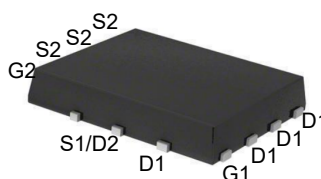
| BVDSS | RDSON | ID   |
|-------|-------|------|
| 30V   | 7mΩ   | 30 A |

### Description

The UD30J03D is the high cell density trench N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The UD30J03D meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### DFN3030-8L Pin Configuration



### Absolute Maximum Ratings

| Symbol                     | Parameter                                             | Rating     | Units            |
|----------------------------|-------------------------------------------------------|------------|------------------|
| $V_{DS}$                   | Drain-Source Voltage                                  | 30         | V                |
| $V_{GS}$                   | Gate-Source Voltage                                   | $\pm 20$   | V                |
| $I_D@T_A=25^\circ\text{C}$ | Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup> | 30         | A                |
| $I_D@T_A=70^\circ\text{C}$ | Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup> | 20         | A                |
| $I_{DM}$                   | Pulsed Drain Current <sup>2</sup>                     | 90         | A                |
| EAS                        | Single Pulse Avalanche Energy <sup>3</sup>            | 39         | mJ               |
| $I_{AS}$                   | Avalanche Current                                     | 30         | A                |
| $P_D@T_A=25^\circ\text{C}$ | Total Power Dissipation <sup>4</sup>                  | 15         | W                |
| $T_{STG}$                  | Storage Temperature Range                             | -55 to 150 | $^\circ\text{C}$ |
| $T_J$                      | Operating Junction Temperature Range                  | -55 to 150 | $^\circ\text{C}$ |

### Thermal Data

| Symbol          | Parameter                                        | Typ. | Max. | Unit               |
|-----------------|--------------------------------------------------|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient <sup>1</sup> | ---  | 85   | $^\circ\text{C/W}$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol                       | Parameter                                      | Conditions                                                | Min. | Typ.  | Max.      | Unit                |
|------------------------------|------------------------------------------------|-----------------------------------------------------------|------|-------|-----------|---------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                              | 30   | ---   | ---       | V                   |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^\circ\text{C}$ , $I_D=1mA$               | ---  | 0.034 | ---       | $V/^\circ\text{C}$  |
| $R_{DS(on)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=7A$                                   | ---  | 7     | 9         | $m\Omega$           |
|                              |                                                | $V_{GS}=4.5V$ , $I_D=4A$                                  | ---  | 10    | 13        |                     |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                          | 1.2  | 1.5   | 2.5       | V                   |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |                                                           | ---  | -3.84 | ---       | $mV/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$       | ---  | ---   | 1         | $\mu A$             |
|                              |                                                | $V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=55^\circ\text{C}$       | ---  | ---   | 5         |                     |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                            | ---  | ---   | $\pm 100$ | nA                  |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1MHz$                      | ---  | 1.04  | 2.1       | $\Omega$            |
| $Q_g$                        | Total Gate Charge (4.5V)                       | $V_{DS}=15V$ , $V_{GS}=4.5V$ , $I_D=7A$                   | ---  | 8.4   | ---       | nC                  |
| $Q_{gs}$                     | Gate-Source Charge                             |                                                           | ---  | 3.1   | ---       |                     |
| $Q_{gd}$                     | Gate-Drain Charge                              |                                                           | ---  | 2.8   | ---       |                     |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=15V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$<br>$I_D=7A$ | ---  | 2.4   | ---       | ns                  |
| $T_r$                        | Rise Time                                      |                                                           | ---  | 72.0  | ---       |                     |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |                                                           | ---  | 36.0  | ---       |                     |
| $T_f$                        | Fall Time                                      |                                                           | ---  | 14.4  | ---       |                     |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V$ , $V_{GS}=0V$ , $f=1MHz$                     | ---  | 816   | ---       | pF                  |
| $C_{oss}$                    | Output Capacitance                             |                                                           | ---  | 107.8 | ---       |                     |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |                                                           | ---  | 82.6  | ---       |                     |

**Diode Characteristics**

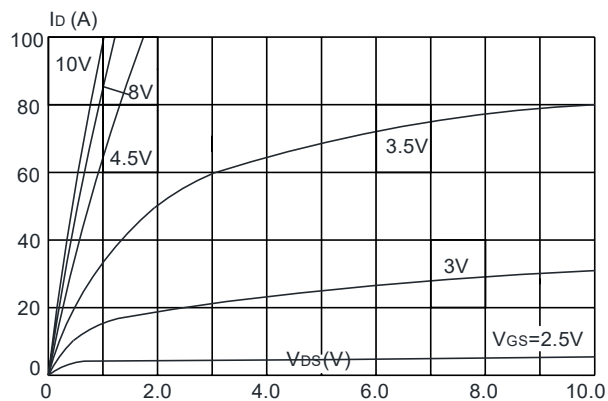
| Symbol   | Parameter                                | Conditions                                      | Min. | Typ. | Max. | Unit |
|----------|------------------------------------------|-------------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current                    | ---  | ---  | 30   | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,5</sup>     |                                                 | ---  | ---  | 30   | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ\text{C}$ | ---  | ---  | 1.2  | V    |

Note :

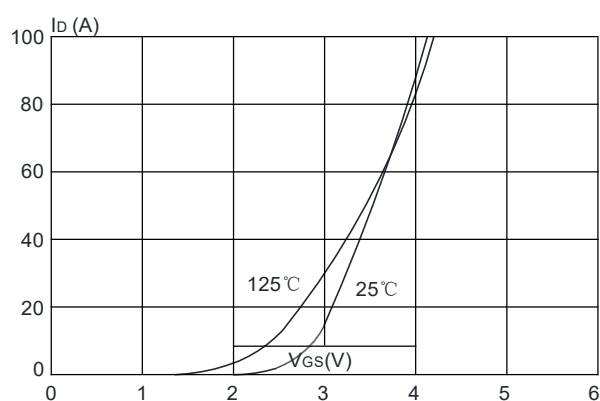
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=20A$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Typical Performance Characteristics

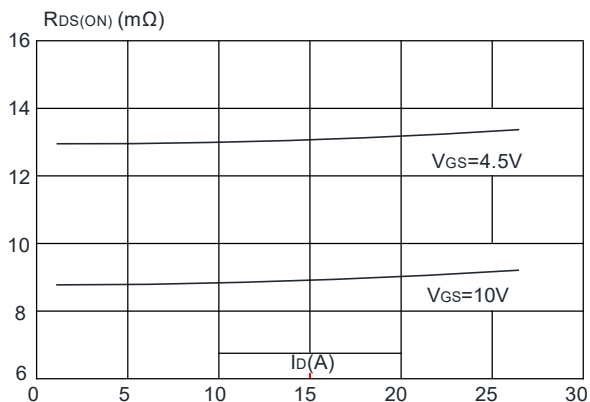
**Figure 1:** Output Characteristics



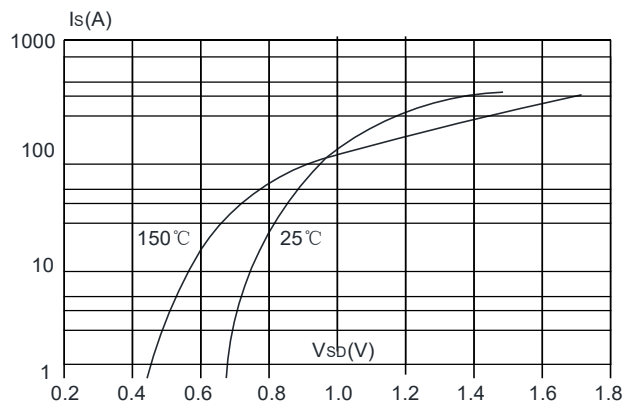
**Figure 2:** Typical Transfer Characteristics



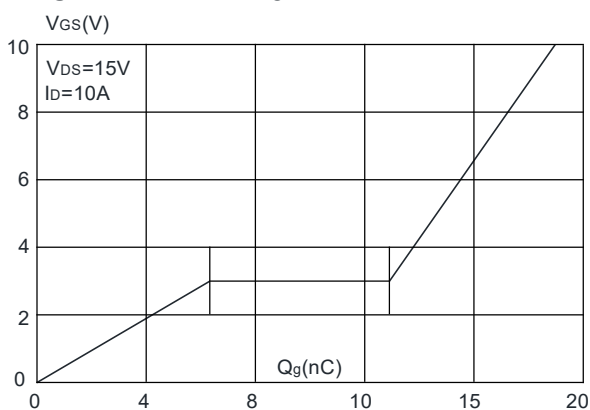
**Figure 3:** On-resistance vs. Drain Current



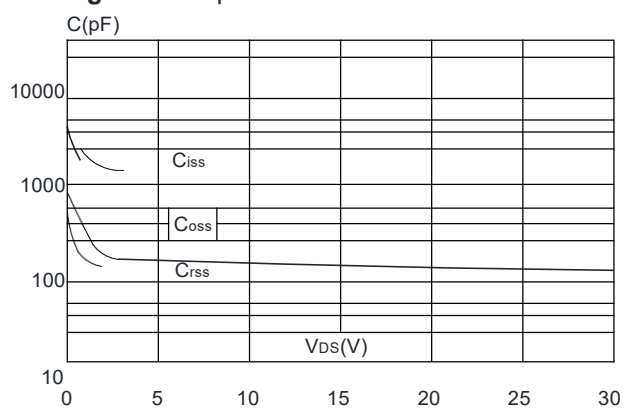
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

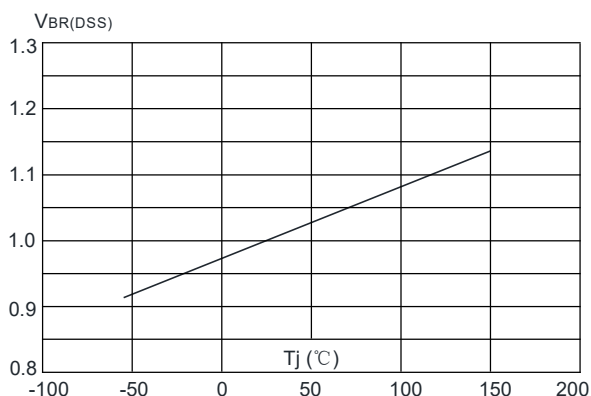


**Figure 6:** Capacitance Characteristics

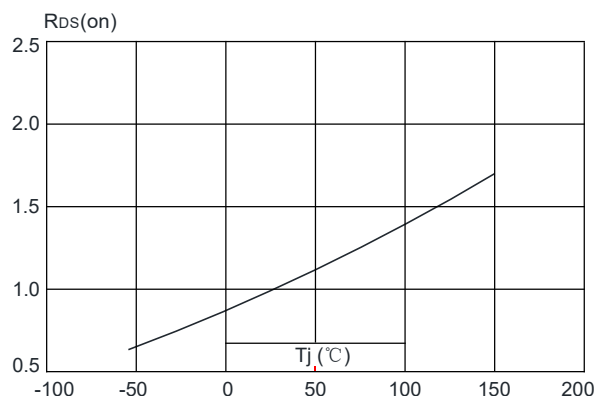


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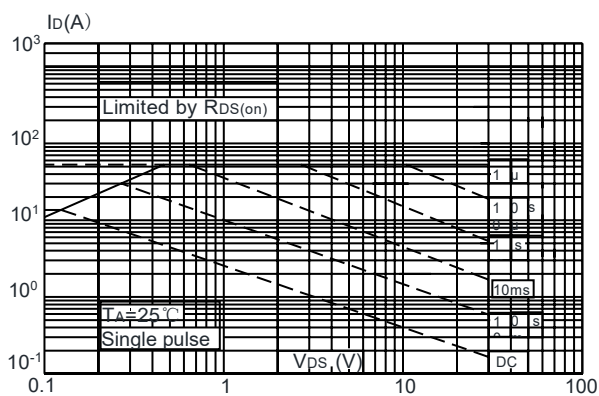
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



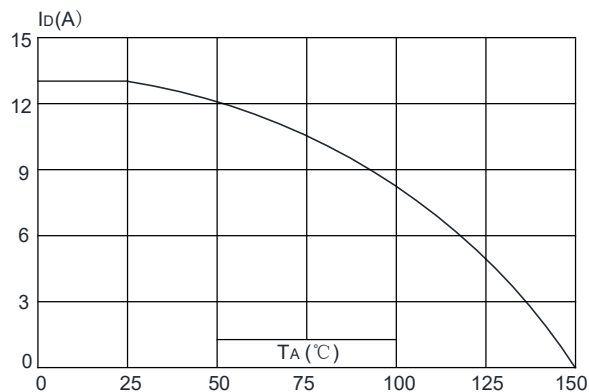
**Figure 8:** Normalized on Resistance vs. Junction Temperature



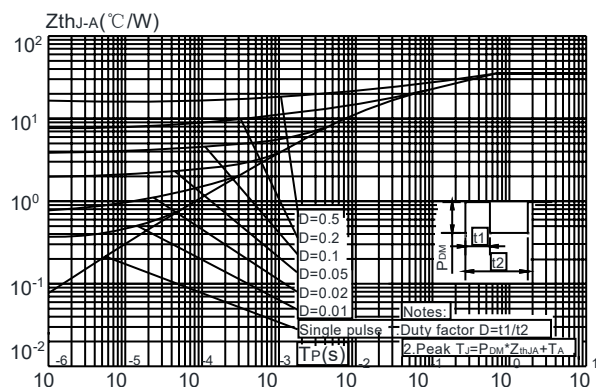
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Test Circuit

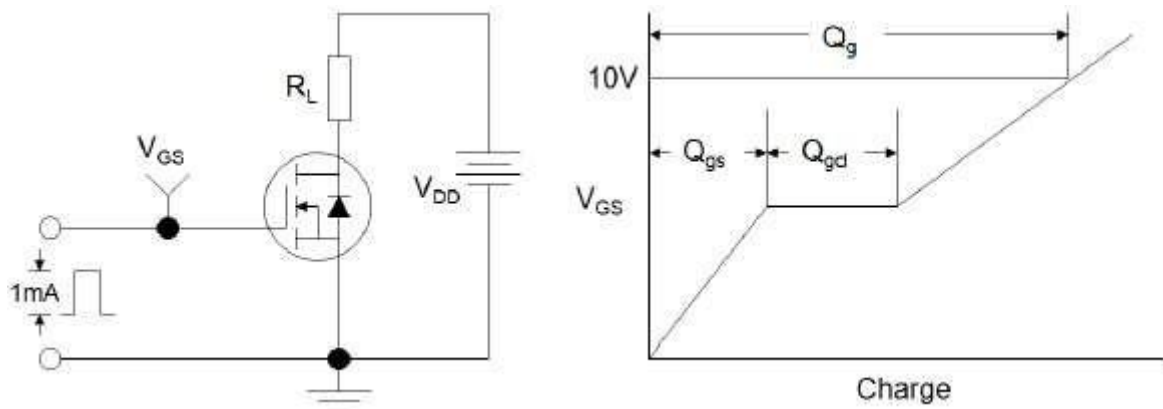


Figure1:Gate Charge Test Circuit & Waveform

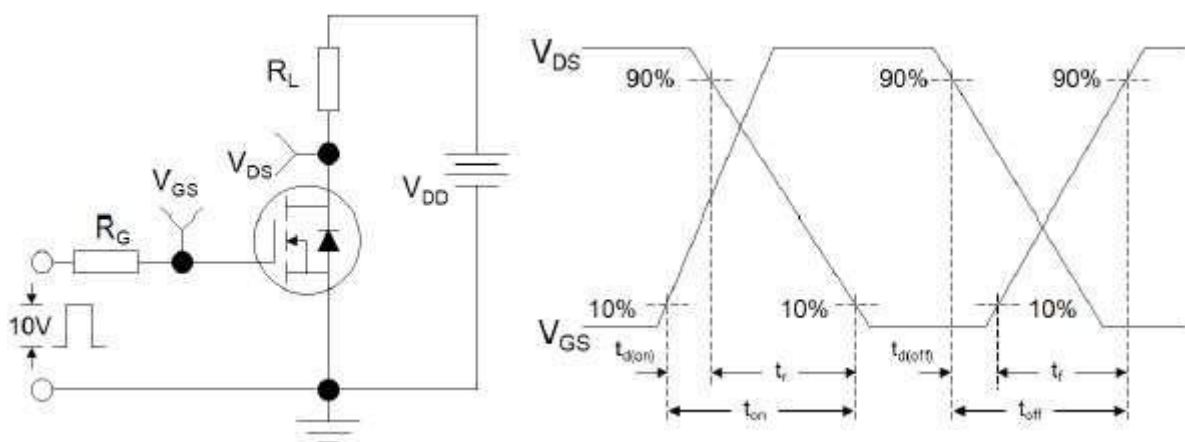


Figure 2: Resistive Switching Test Circuit & Waveforms

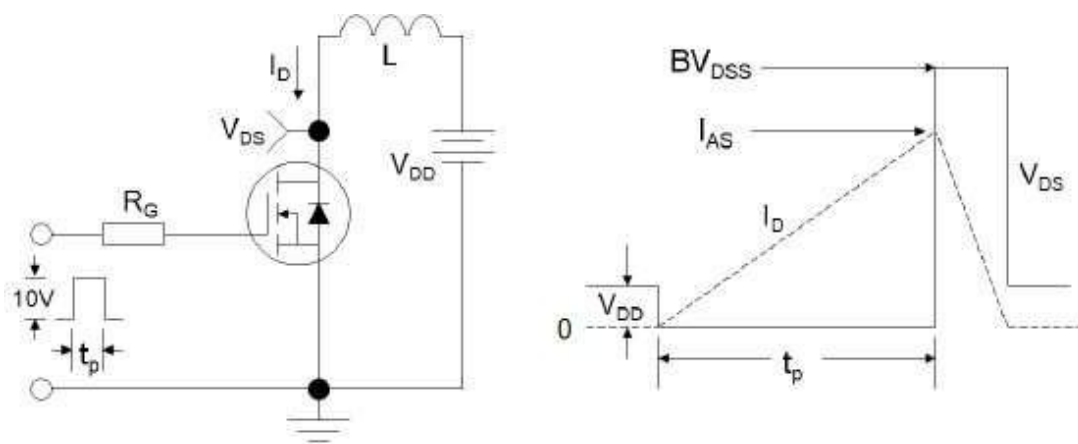
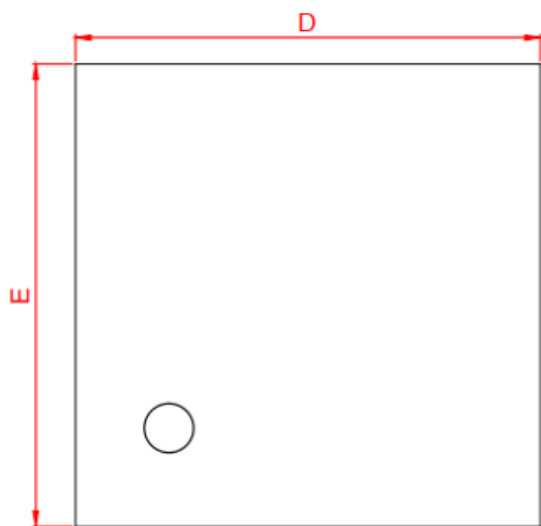
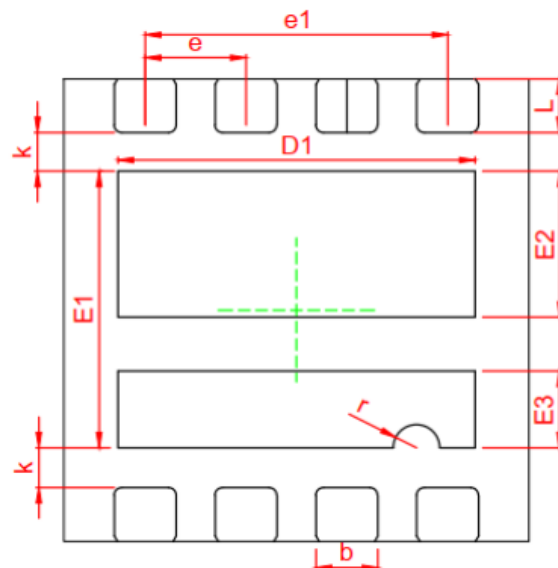


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

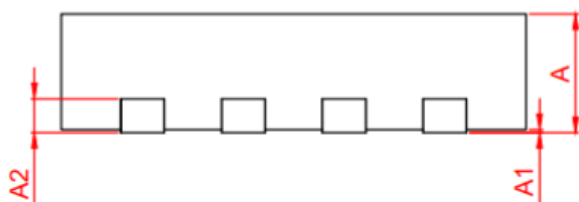
## Package Mechanical Data-DFN3030-8L-Single



TOP VIEW



BOTTOM VIEW



| SYMBOL | MILLIMETER |      |      |
|--------|------------|------|------|
|        | MIN        | NOM  | MAX  |
| A      | 0.70       | 0.75 | 0.80 |
| * A1   | 0.00       | 0.02 | 0.05 |
| * b    | 0.35       | 0.40 | 0.40 |
| * A2   | 0.203 BSC  |      |      |
| * D    | 2.95       | 3.00 | 3.05 |
| * E    | 2.95       | 3.00 | 3.05 |
| * D1   | 2.25       | 2.30 | 2.35 |
| * E1   | 1.70       | 1.80 | 1.90 |
| * E2   | 0.90       | 0.95 | 1.00 |
| * E3   | 0.45       | 0.50 | 0.55 |
| * e    | 0.65 BSC   |      |      |
| * e1   | 1.95 BSC   |      |      |
| * k    | 0.20       | 0.25 | 0.30 |
| * L    | 0.30       | 0.35 | 0.40 |
| r      | 0.15 REF   |      |      |